

1           7.       (Amended) The method of claim 6, further comprising attaching a solder ball  
2 to the substrate.

1           8.       (Amended) The method of claim 5, further comprising molding an  
2 encapsulant onto the substrate and the integrated circuit.

1           9.       A method for assembling an integrated circuit package, comprising:  
2 applying an epoxy to a thermal element;  
3 placing the epoxy and the thermal element onto an integrated circuit; and,  
4 curing the epoxy with energy at a microwave frequency.

1           10.      (Amended) The method of claim 9, further comprising mounting the  
2 integrated circuit to a substrate.

1           11.      (Amended) The method of claim 10, further comprising attaching a solder ball  
2 to the substrate.

*B1*  
*cont*  
1           12.      (Amended) The method of claim 9, further comprising molding an  
2 encapsulant onto the substrate and the integrated circuit.

1           13.      The method of claim 5, wherein said thermal element is a heat spreader.

1           14.      The method of claim 5, wherein prior to applying said epoxy, the method  
2 further comprises providing a thermally conductive filler to a resin to form said epoxy.

1           15.      The method of claim 14, wherein said thermally conductive filler includes  
2 carbon particles.

1           16.      The method of claim 5, wherein said placing of said thermal element includes  
2 attaching said thermal element to said epoxy.

1           17.      The method of claim 5, wherein said curing of the epoxy includes

2 selecting the microwave frequency to cure the epoxy without damaging the integrated  
3 circuit or heating other components within the integrated circuit package; and  
4 generating energy at the microwave frequency by a microwave generator directed  
5 toward the epoxy.

1 18. The method of claim 9, wherein prior to applying said epoxy to the thermal  
2 element, the method further comprises providing a thermally conductive filler to a resin to  
3 form said epoxy.

*B1*  
*cont*  
1 19. The method of claim 10 further comprising baking the substrate before curing  
2 the epoxy.

1 20. The method of claim 9, wherein said curing of the epoxy includes  
2 selecting the microwave frequency to cure the epoxy without damaging the integrated  
3 circuit or heating other components within the integrated circuit package; and  
4 generating energy at the microwave frequency by a microwave generator directed  
5 toward the epoxy.